# **LNJ236W82RA**

### Hight Bright Surface Mounting Chip LED

#### ESS Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

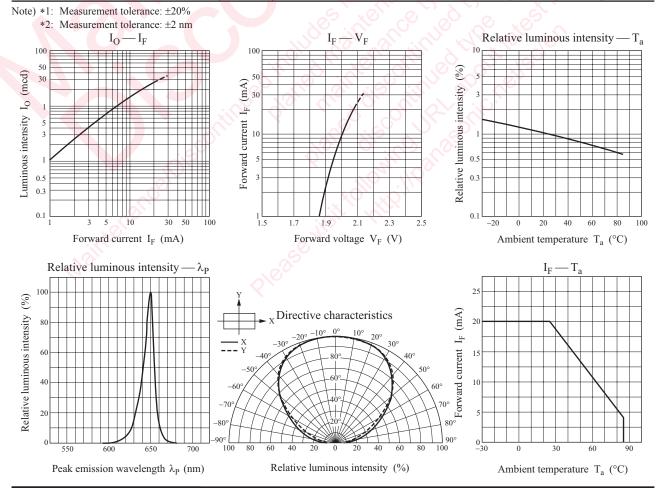
Parameter	Symbol	Rating	Unit	
Power dissipation	PD	55	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Lighting Color

• Red

#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

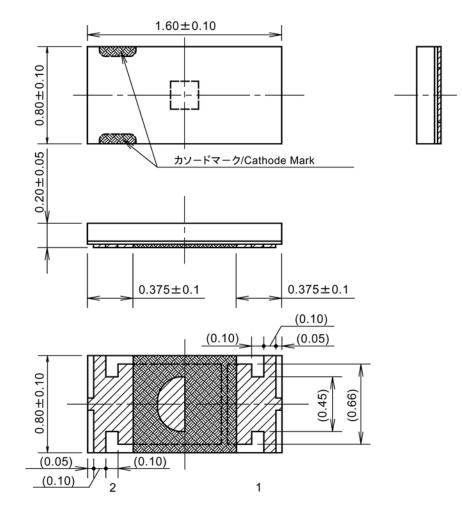
1 of ward current	TF	20	IIIIX				
Pulse forward current *	$I_{FP}$	60	mA				
Reverse voltage	V <sub>R</sub>	4	V				
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C				
Storage temperature	T <sub>stg</sub>	-40 to +100	°C				
Note) *: The condition of I <sub>FP</sub> is duty 10%, Pulse	width 1 mse	с.					
Electro-Optical Characteristics T <sub>a</sub> =	= 25°C±3°	С					
Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Luminous intensity *1	Io	$I_F = 5 \text{ mA}$		5.8	7.0	26.8	mcd
Reverse current	I <sub>R</sub>	$V_R = 4 V$				100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$	40° 0		1.95	2.30	V
Peak emission wavelength	λ <sub>P</sub>	$I_F = 5 \text{ mA}$	9 m Cn;		645		nm
Dominant emission wavelength *2	$\lambda_{d}$	$I_F = 5 \text{ mA}$	Nº CO	620	630	640	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$	0110 200 -18	18	20 .		nm



Publication date: December 2008

Package (Unit: mm)

## KLTFTN2K3600



• Pin name

1: Anode

2: Cathode

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